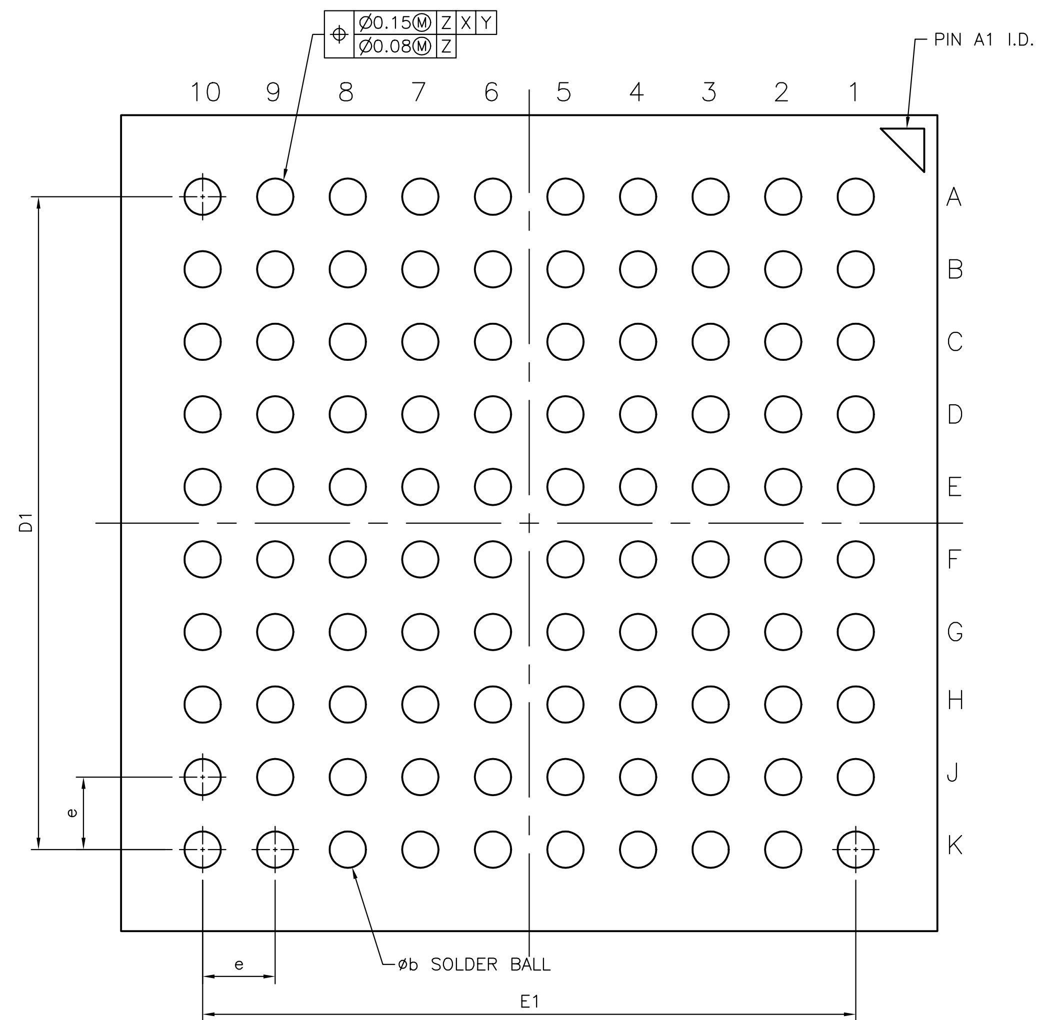

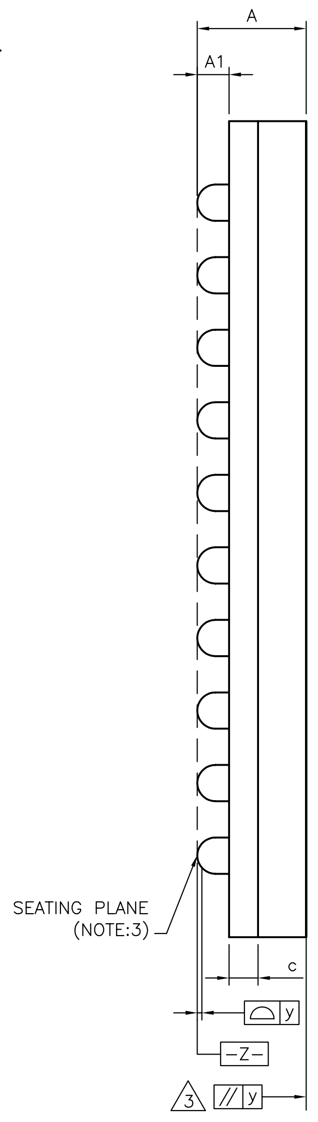

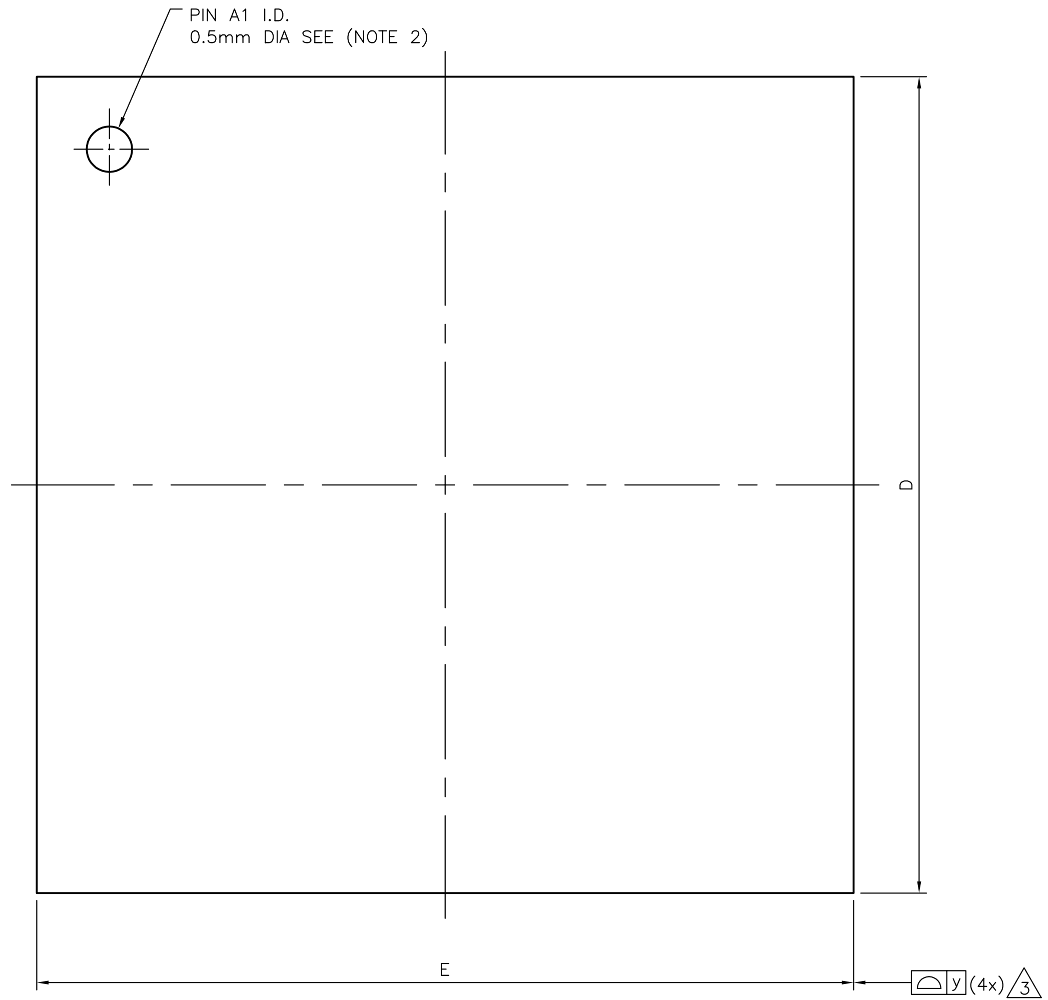

SYMBOLS	DIMENSIONS IN MILLIMETERS		
	MIN	NOM	MAX
A	1.10	1.20	1.30
A1	0.30	0.35	0.40
øb	0.35	0.40	0.45
c	---	0.32	---
D	8.95	9.00	9.05
D1	---	7.20	---
E	8.95	9.00	9.05
E1	---	7.20	---
e	---	0.80	---
y	0.00	——	0.10

NOTE :

1. ALL DIMENSION ARE IN MILLIMETERS.
2. PIN A1 ID. TO BE MARKED BY LASER.
3. PRIMARY DATUM -Z- AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. "e" REPRESENTS THE MAXIMUM SOLDER BALL GRID PITCH.
5. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL PITCH. PARALLEL TO PRIMARY DATUM -Z- .

CUSTOMER :		LINGSEN PRECISION IND., LTD. 5-1 NAN 2ND ROAD T.E.P.Z TAICHUNG., TAIWAN. R. O. C
APPROVED BY	DATE	TITLE: MINI BGA 100L(9x9mm) PACKAGE OUTLINE DRAWING
DRAW BY: Sandy Sue	05/05/'06	
CHECK BY: S. S. Lin	05/05/'06	
APPROVAL: Kevin Liao	05/09/'06	DWG. NO. PO-MBGA-021 REV. 3
APPROVAL: Jack Tu	05/09/'06	UNIT : mm SCALE : 15/1 SHEET 1 OF 1